

# PHASE CHANGE MATERIAL TRANSIENT HEATSINK FOR POWER SEMICONDUCTOR

Midterm Presentation I

Team 9:

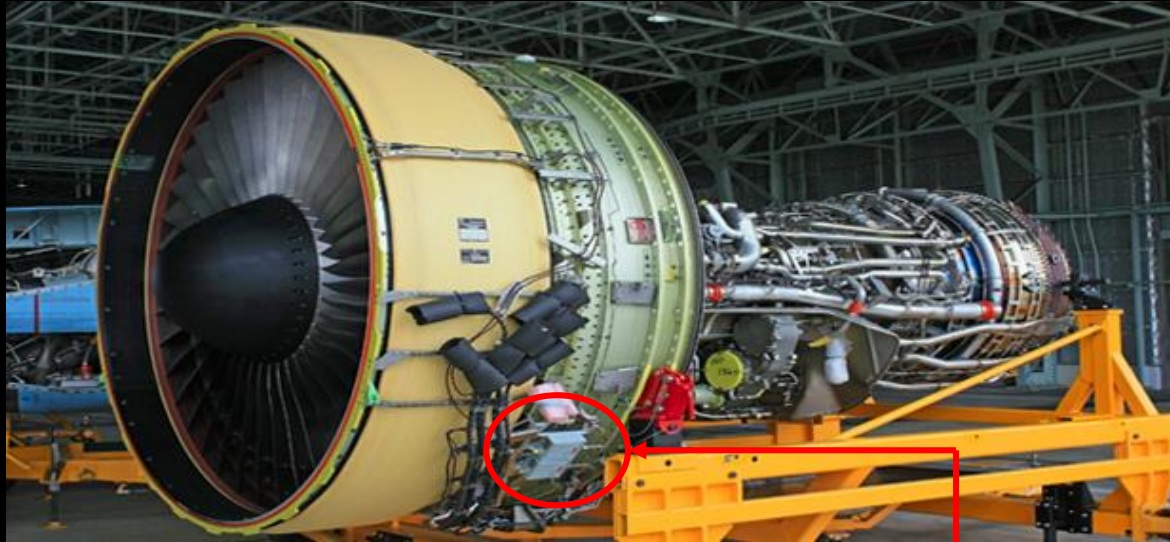
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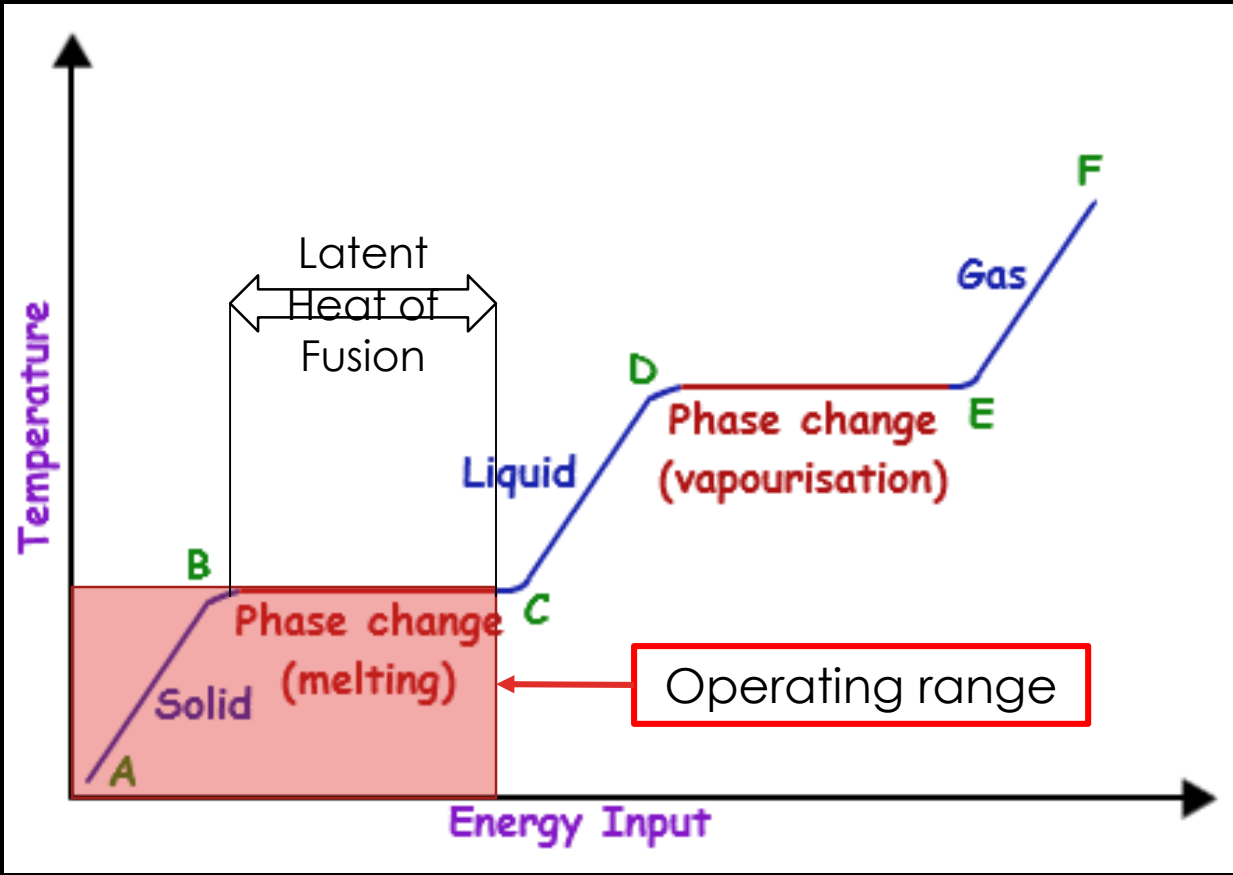
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# MOTIVATION



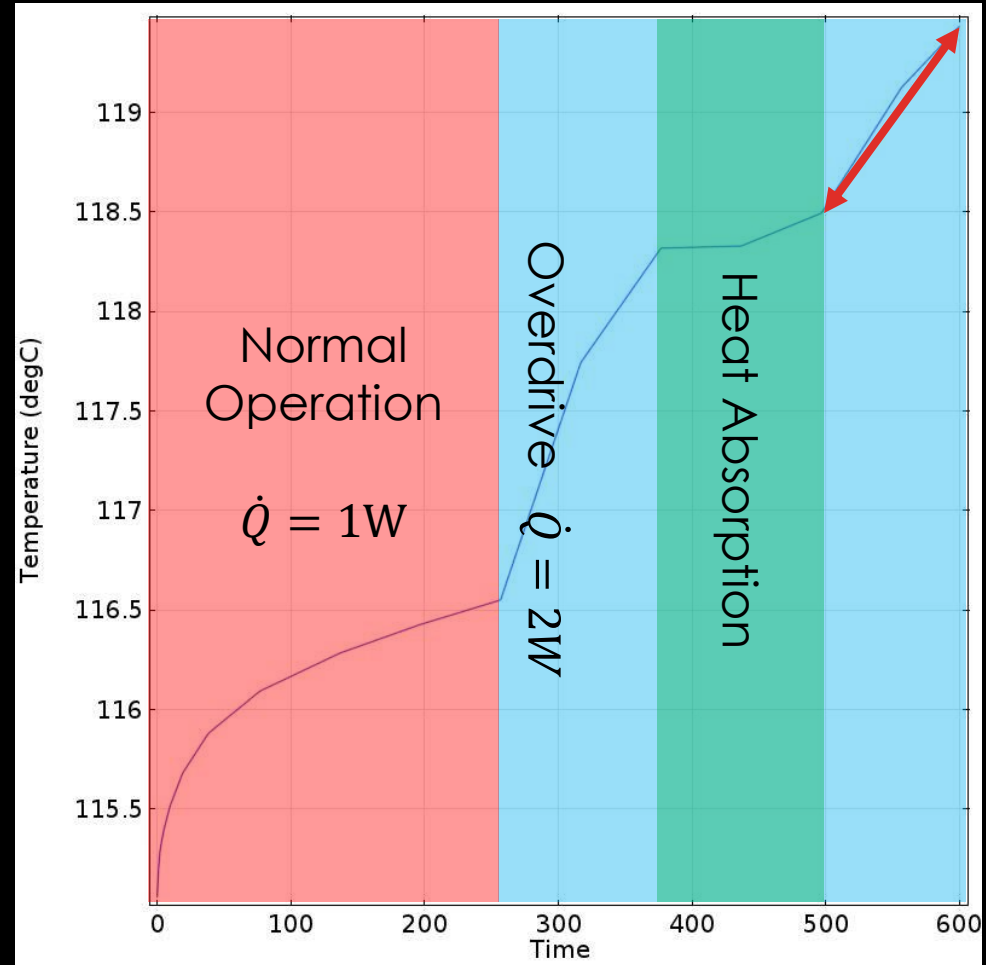
- New solutions for electronics cooling
- Power Semiconductors
  - Found in jet engine's ignition units and power regulators
  - Thermal management is critical
- Customer's need
  - A highly-reliable, low-weight heat dissipation solution for power semiconductors in jet engine systems

# BACKGROUND



# OBJECTIVES

- Identify ideal PCM for heatsink
  - Given operating temperature range 115-125°C
- Numerical model to test heatsink performance
  - Design parameters
  - Prototype geometry
- An experimental rig for validation of the model
  - Final design selection/design for manufacturing



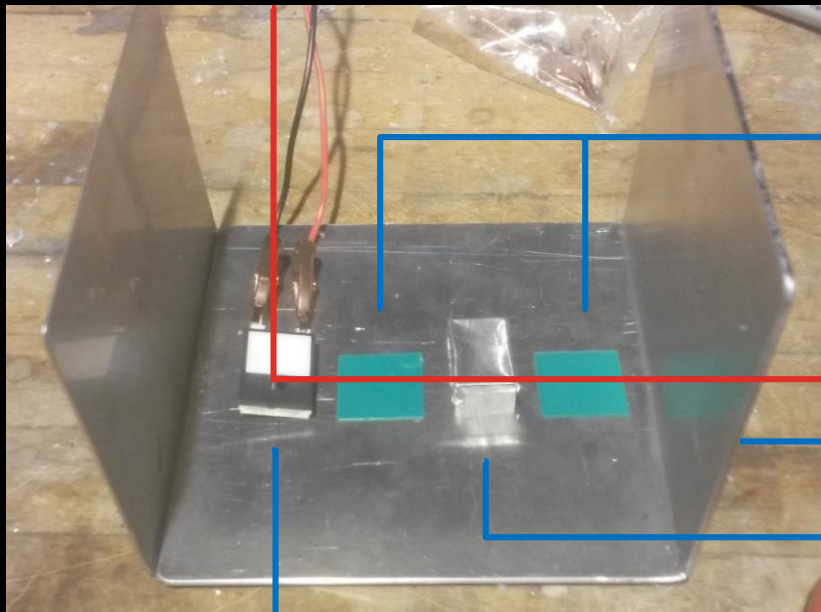
# PROCUREMENT

Material/Equipment	Vendor	Amount	Unit Cost (USD)	Total Cost (USD)
MP9100 resistor	Digi-Key	1 pc.	10.90	10.90
52In-48Sn solder	IndiumCorp	3 ft	265.00	795.00
Aluminum tape	eBay	1 spool	40.00	40.00
Hi-Flow 300P*	Orion	1 pc.	48.00	48.00
NI 9211*	National Instruments	1 pc.	351.00	<b>351.00</b>
cDAQ 9174*	National Instruments	1 pc.	762.00	<b>762.00</b>
LabView Full	National Instruments	1 license	2699.00	<b>2699.00</b>
DC power supply*	Digi-Key	1 pc.	489.00	<b>489.00</b>
Lab oven*	Mellen	1 pc.	2499.99	<b>2499.99</b>
Type K thermocouple*	Omega	4 pcs.	30.00	120.00
Aluminum bar*	Various	26 cu. in.	5.00	5.00
Thermal contact tape*	eBay	1 spool	4.50	4.50
Machining*	N/A	2 hours	20.00	40.00
<b>Remaining Budget (including starred items):</b>				<b>-5864.39</b>
<b>Remaining Budget (excluding starred items):</b>				<b>1154.10</b>

Starred items obtained at no cost

- Allocated budget was \$2,000
  - Majority of cost would be incurred in purchasing testing equipment: One-time capital investments
  - Still well under-budget (excluding starred items) and do not anticipate any other major purchases

# PROTOTYPE TESTING



Thermal interface material

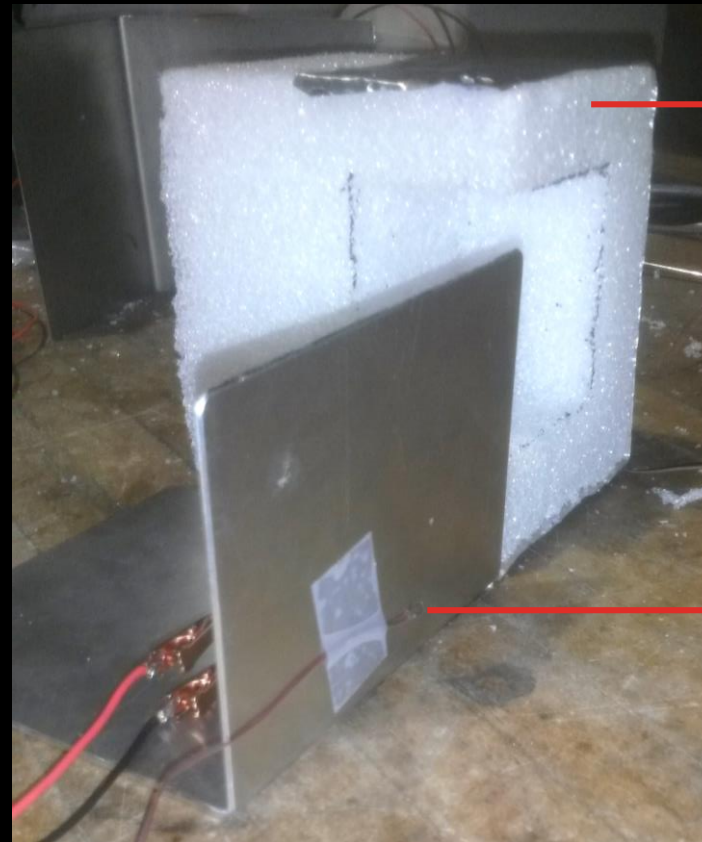
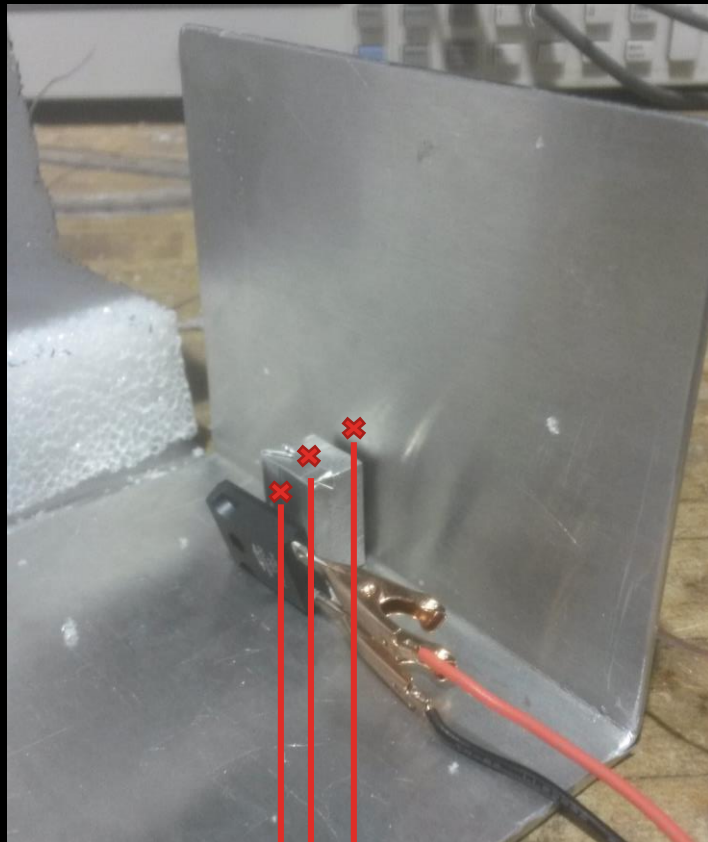
Direction of heat transfer

Enclosure wall

Heatsink

Resistor

# PROTOTYPE TESTING



Styrofoam insulation

Type E thermocouple

Thermocouple mount locations

# PROTOTYPE TESTING



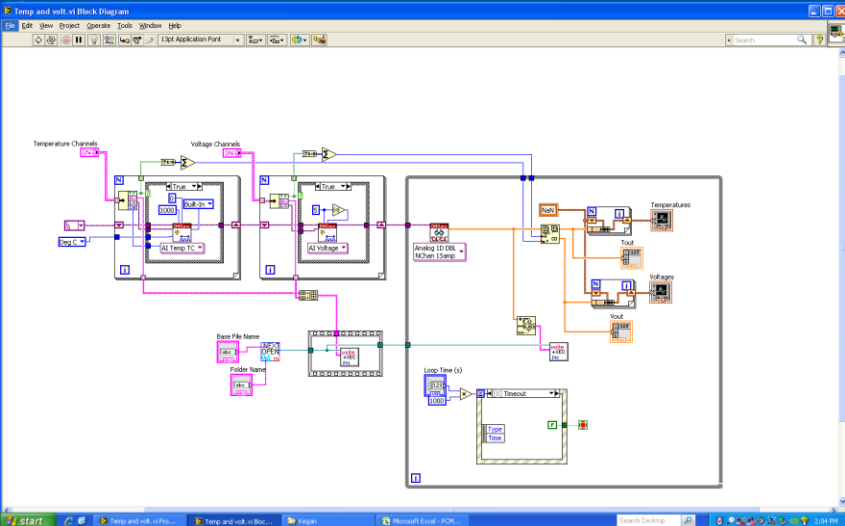
Leads to DC supply

Leads to DAQ



Exit port for leads

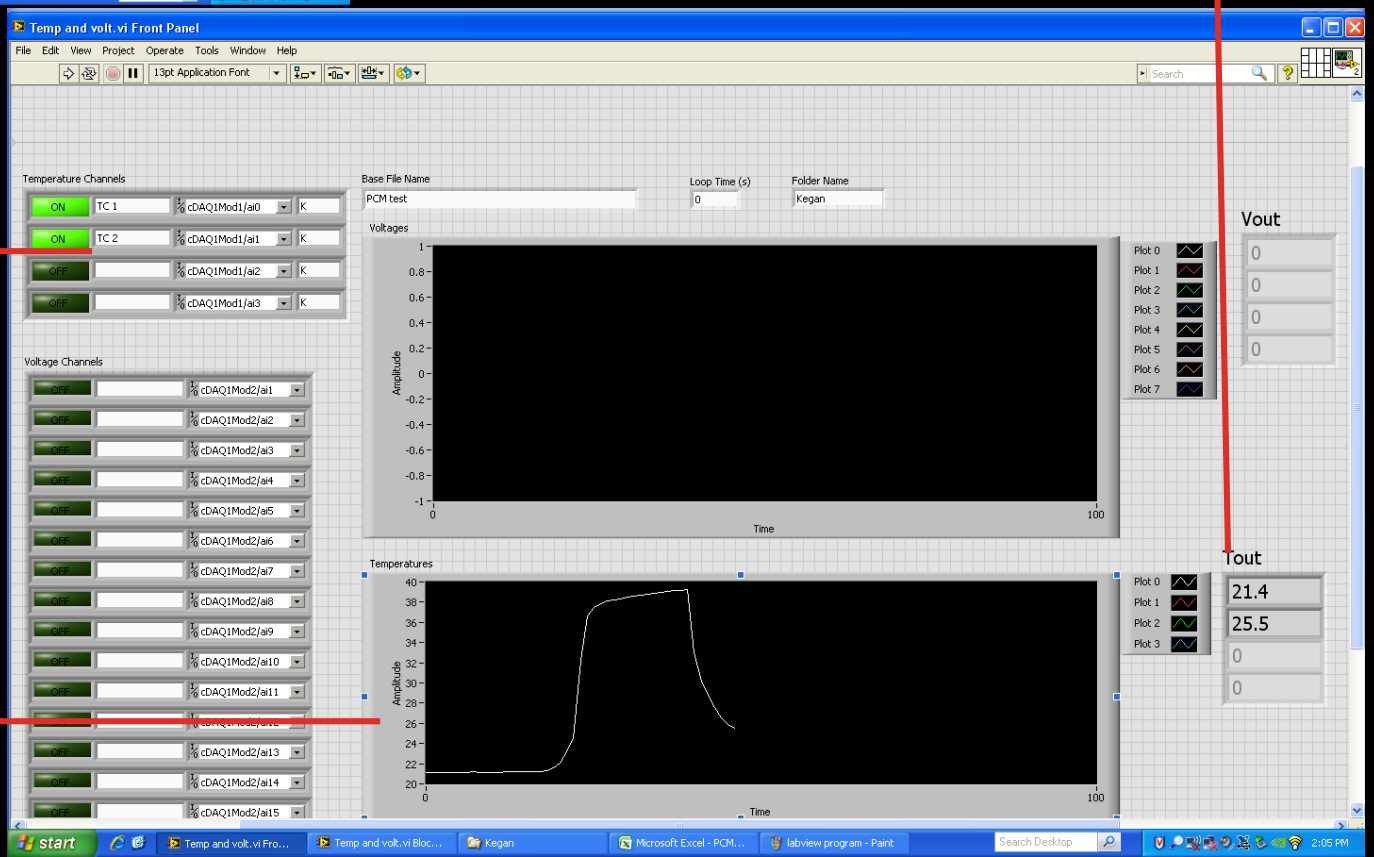




# DAQ

Real-time temperature

Thermocouple On/Off switch



Real-time temperature

# CALIBRATION

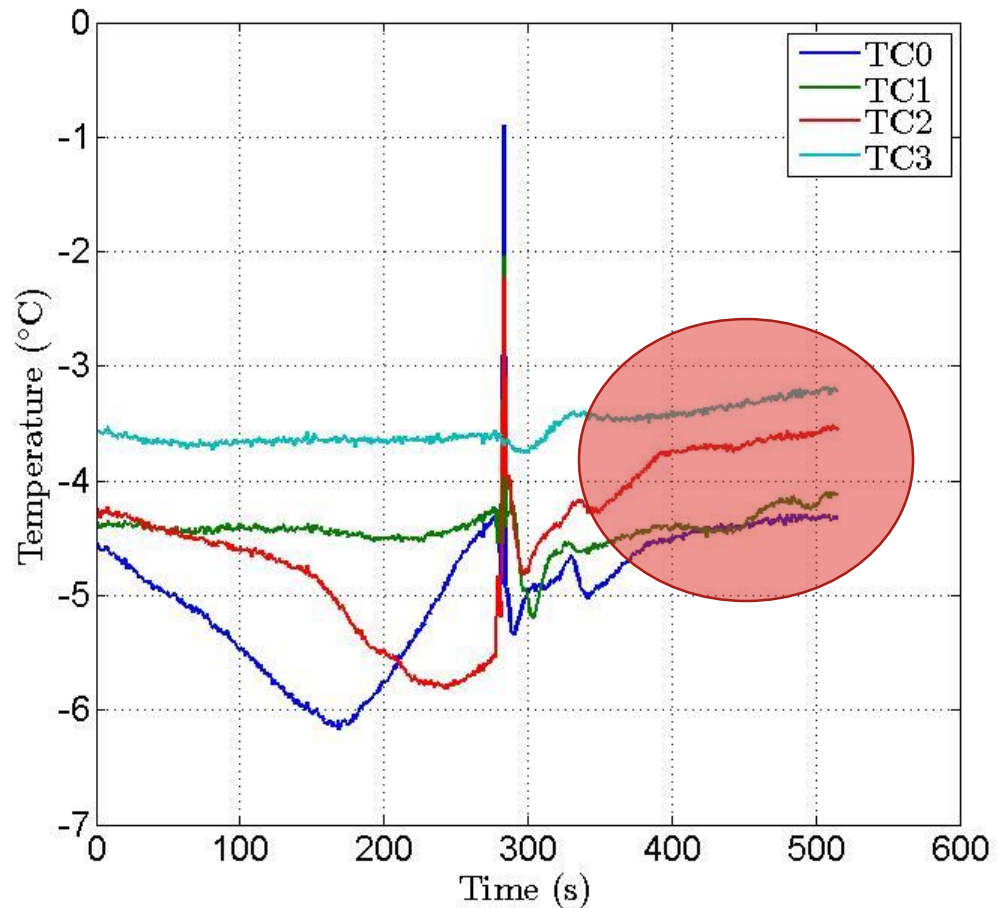


Thermocouple junction  
point

Ice Water

# CALIBRATION

- $T_0 = -4.3651$
- $T_1 = -4.2870$
- $T_2 = -3.6437$
- $T_3 = -3.2951$



# PERSONAL PROTECTION EQUIPMENT (PPE)



Safety Glasses

Long Sleeves

Thermally  
Insulated Gloves

# FUTURE PLANS

- Finish prototyping
  - Setting up test rig, troubleshooting, executing validation
- Refine model - if necessary
- Determine manufacturing method

# ACKNOWLEDGEMENTS

- Bob Walsh - NHMFL
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- Scott Hill – NHMFL
- Jun Lu – NHMFL
- Charlie Carbiener – STRIDE Lab



QUESTIONS?